

US00D790491S

(12) **United States Design Patent** (10) **Patent No.:** **US D790,491 S**  
**Hayashida et al.** (45) **Date of Patent:** **\*\* Jun. 27, 2017**

(54) **POWER SEMICONDUCTOR DEVICE**

H02B 6/4201; G02B 6/4256; G02B 6/4257; G02B 6/4261; G02B 6/4262; G02B 6/428;

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(Continued)

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(56) **References Cited**

**U.S. PATENT DOCUMENTS**

5,347,160 A \* 9/1994 Sutrina ..... H01L 24/72 257/678

D364,383 S \* 11/1995 Yamada ..... D13/146

(Continued)

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(\*\*) Term: **15 Years**

(21) Appl. No.: **29/558,563**

(57) **CLAIM**

The ornamental design for a power semiconductor device, as shown and described.

(22) Filed: **Mar. 18, 2016**

(30) **Foreign Application Priority Data**

**DESCRIPTION**

Sep. 30, 2015 (JP) ..... 2015-021417

(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**

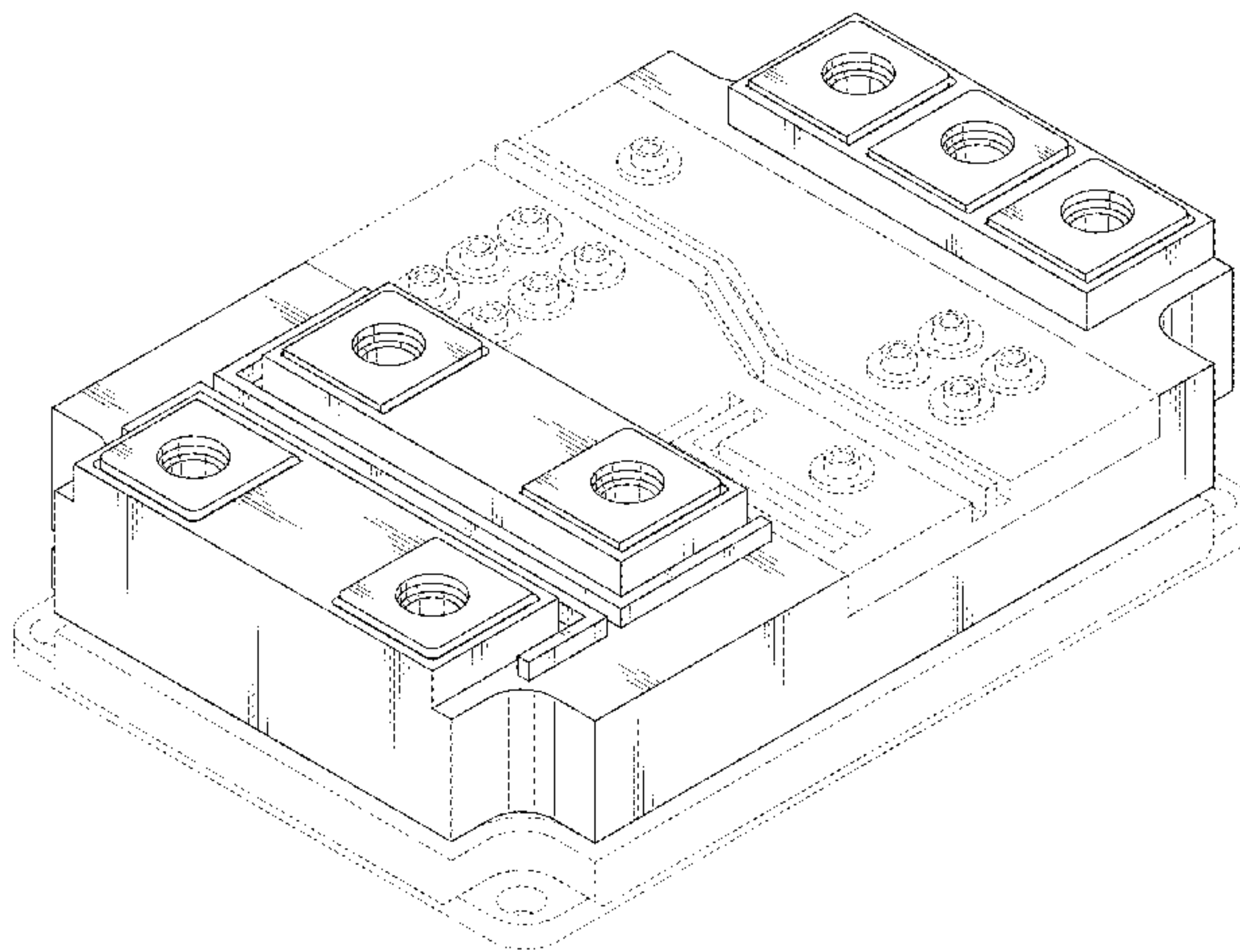
USPC ..... D13/182; 257/678, 684, 690, 691; 361/679.01, 713, 728, 736, 760, 761, 772, 361/775, 783, 820; 174/250, 253; 438/15, 25, 26, 51, 55, 63, 64, 106

CPC . H01L 21/00; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/02; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/17151; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905; H01L 2224/08054; H01L 23/58; H05B 41/14;

FIG. 1 is a front, left side, bottom perspective view of a power semiconductor device, showing our new design; FIG. 2 is a front, right side, top perspective view thereof; FIG. 3 is a front view thereof; FIG. 4 is a rear view thereof; FIG. 5 is a left side view thereof; FIG. 6 is a right side view thereof; FIG. 7 is a top view thereof; FIG. 8 is a bottom view thereof; FIG. 9 is a cross sectional view taken along line 9-9 in FIG. 3; and, FIG. 10 is another cross sectional view taken along line 10-10 in FIG. 3.

The broken line showing of the power semiconductor device is included for the purpose of illustrating portions of the power semiconductor device and forms no part of the claimed design. The dot and dashed lines mean a boundary between the claimed portion and the non-claimed portion.

**1 Claim, 9 Drawing Sheets**



(58) **Field of Classification Search**  
 CPC ..... G02B 6/4281; H05K 1/14; H05K 1/141;  
 H05K 1/142; H05K 1/144; H05K 1/18;  
 H05K 1/181; H05K 1/182; H05K 1/026  
 See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

|            |   |         |               |         |
|------------|---|---------|---------------|---------|
| D364,384 S | * | 11/1995 | Shimizu ..... | D13/146 |
| D364,385 S | * | 11/1995 | Shimizu ..... | D13/146 |
| D441,726 S | * | 5/2001  | Sofue .....   | D13/182 |
| D476,959 S | * | 7/2003  | Yamada .....  | D13/182 |
| D587,662 S | * | 3/2009  | Soutome ..... | D13/182 |
| D589,012 S | * | 3/2009  | Soyano .....  | D13/182 |
| D606,951 S | * | 12/2009 | Soyano .....  | D13/182 |
| D653,633 S | * | 2/2012  | Soyano .....  | D13/182 |
| D653,634 S | * | 2/2012  | Soyano .....  | D13/182 |
| D686,174 S | * | 7/2013  | Soyano .....  | D13/182 |
| D703,625 S | * | 4/2014  | Lim .....     | D13/182 |
| D704,670 S | * | 5/2014  | Chen .....    | D13/182 |

|            |   |         |                   |         |
|------------|---|---------|-------------------|---------|
| D704,671 S | * | 5/2014  | Chen .....        | D13/182 |
| D710,317 S | * | 8/2014  | Chen .....        | D13/182 |
| D710,318 S | * | 8/2014  | Chen .....        | D13/182 |
| D710,319 S | * | 8/2014  | Chen .....        | D13/182 |
| D712,853 S | * | 9/2014  | Nakamura .....    | D13/182 |
| D721,048 S | * | 1/2015  | Nakamura .....    | D13/182 |
| D721,340 S | * | 1/2015  | Nakamura .....    | D13/182 |
| D748,595 S | * | 2/2016  | Bertalan .....    | D13/182 |
| D754,084 S | * | 4/2016  | Kawase .....      | D13/182 |
| D759,604 S | * | 6/2016  | Yoneyama .....    | D13/182 |
| D762,185 S | * | 7/2016  | Muehlensiep ..... | D13/182 |
| D762,597 S | * | 8/2016  | Bertalan .....    | D13/182 |
| D766,851 S | * | 9/2016  | Yoneyama .....    | D13/182 |
| D767,516 S | * | 9/2016  | Yoneyama .....    | D13/182 |
| D769,834 S | * | 10/2016 | Kawase .....      | D13/182 |
| D772,184 S | * | 11/2016 | Soyano .....      | D13/182 |
| D773,412 S | * | 12/2016 | Yoneyama .....    | D13/182 |
| D773,413 S | * | 12/2016 | Yoneyama .....    | D13/182 |
| D774,479 S | * | 12/2016 | Soyano .....      | D13/182 |
| D775,091 S | * | 12/2016 | Edenharter .....  | D13/182 |
| D775,593 S | * | 1/2017  | Edenharter .....  | D13/182 |
| D776,071 S | * | 1/2017  | Edenharter .....  | D13/182 |

\* cited by examiner

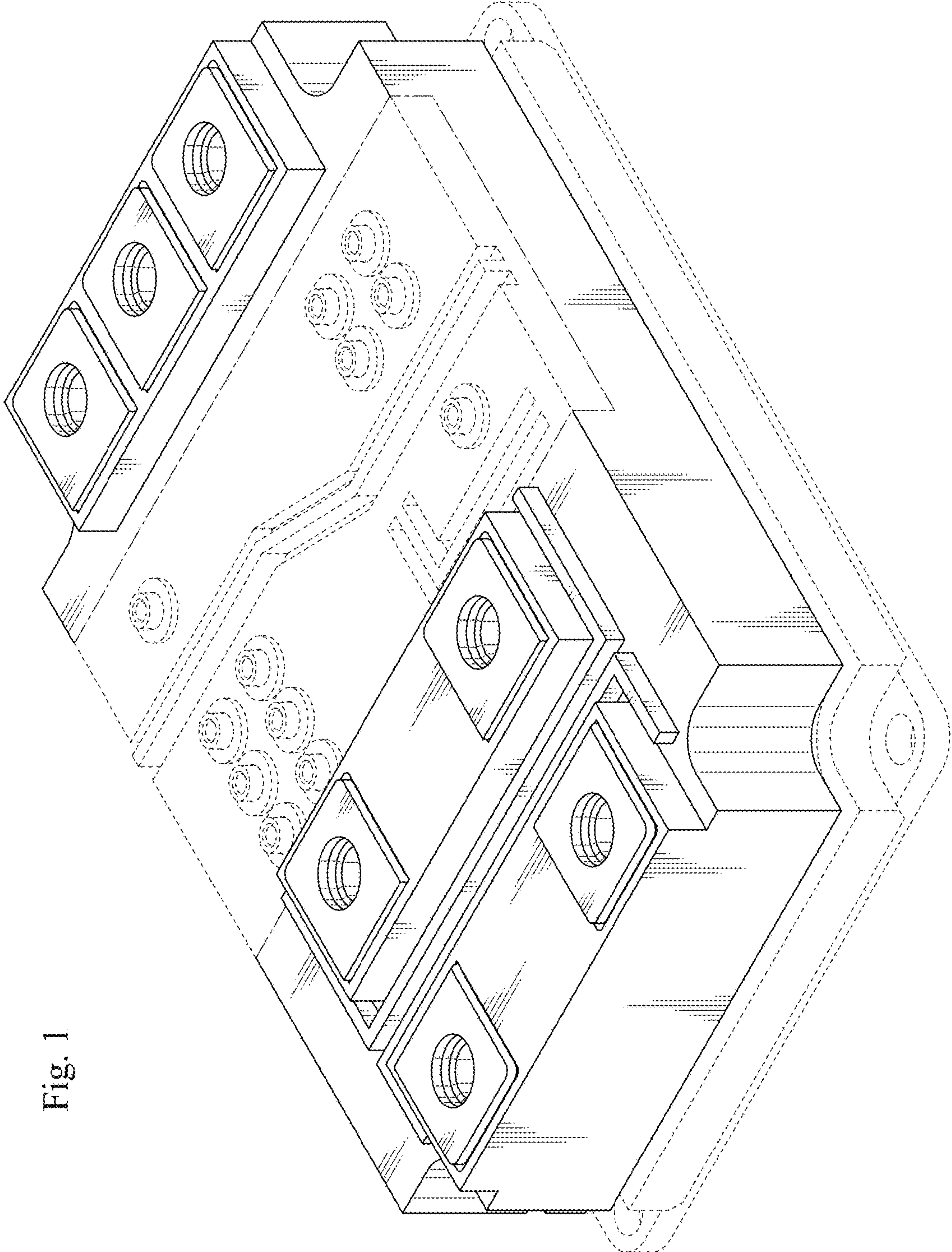


Fig. 1



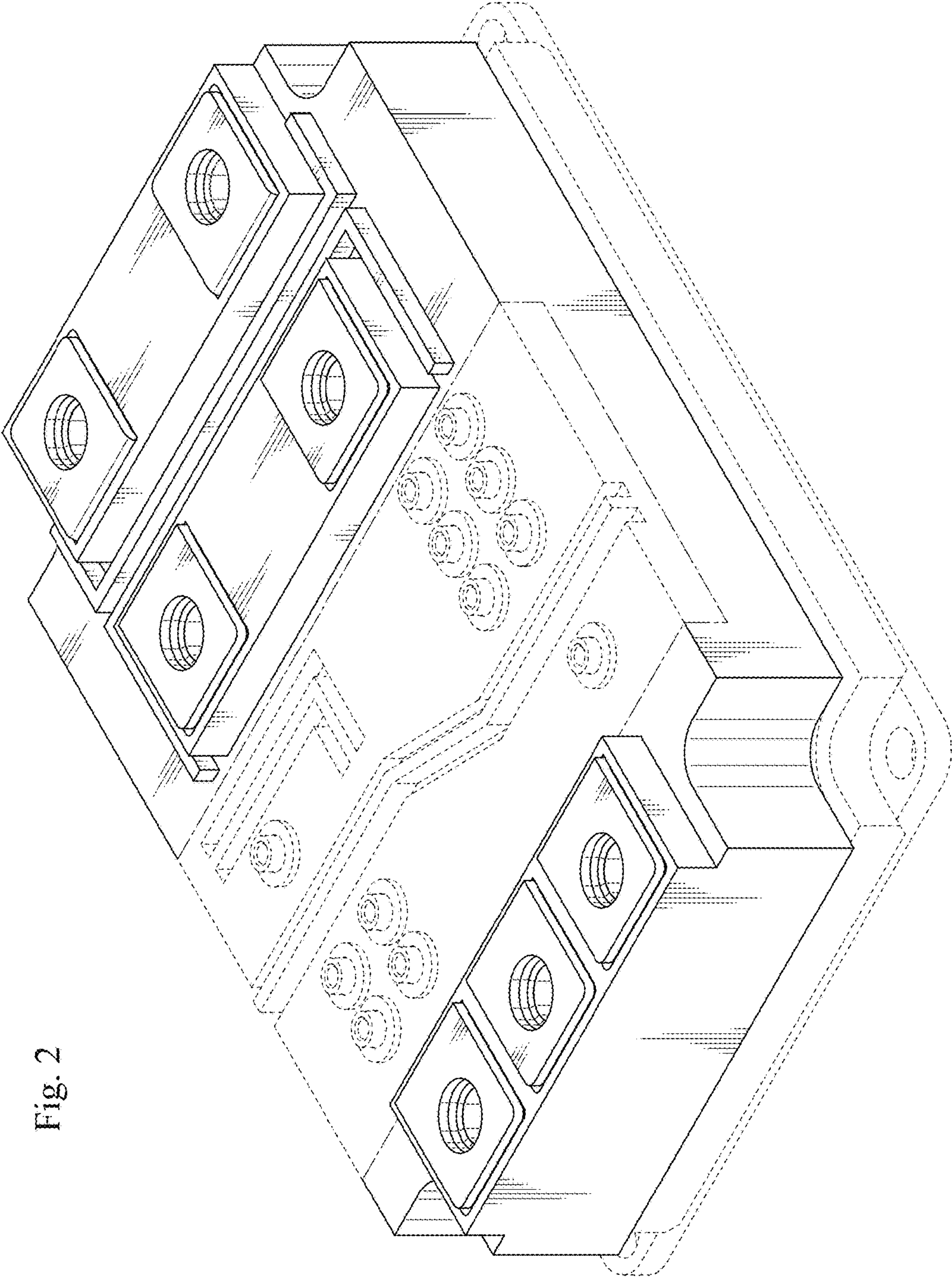


Fig. 2

Fig. 3

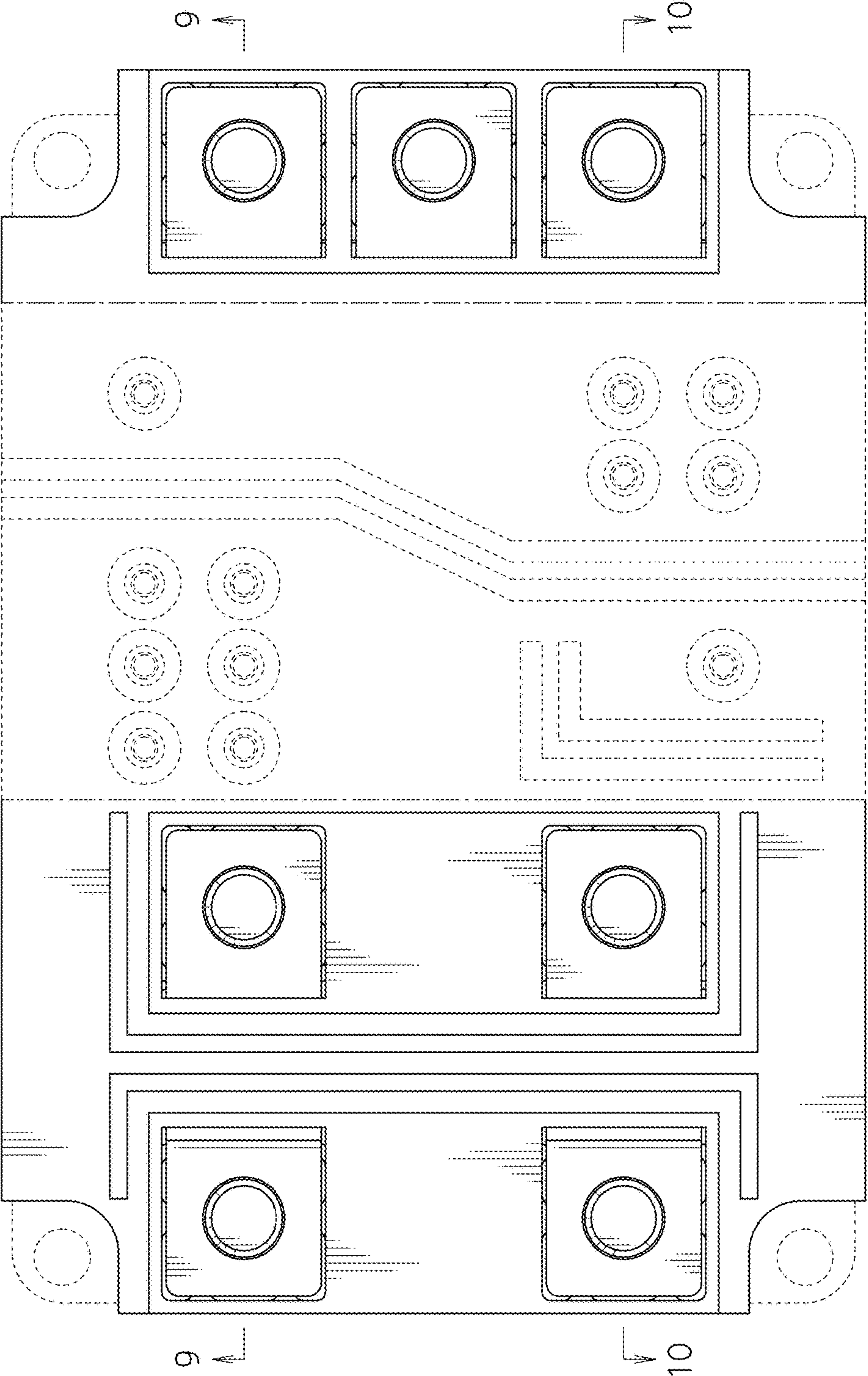


Fig. 4

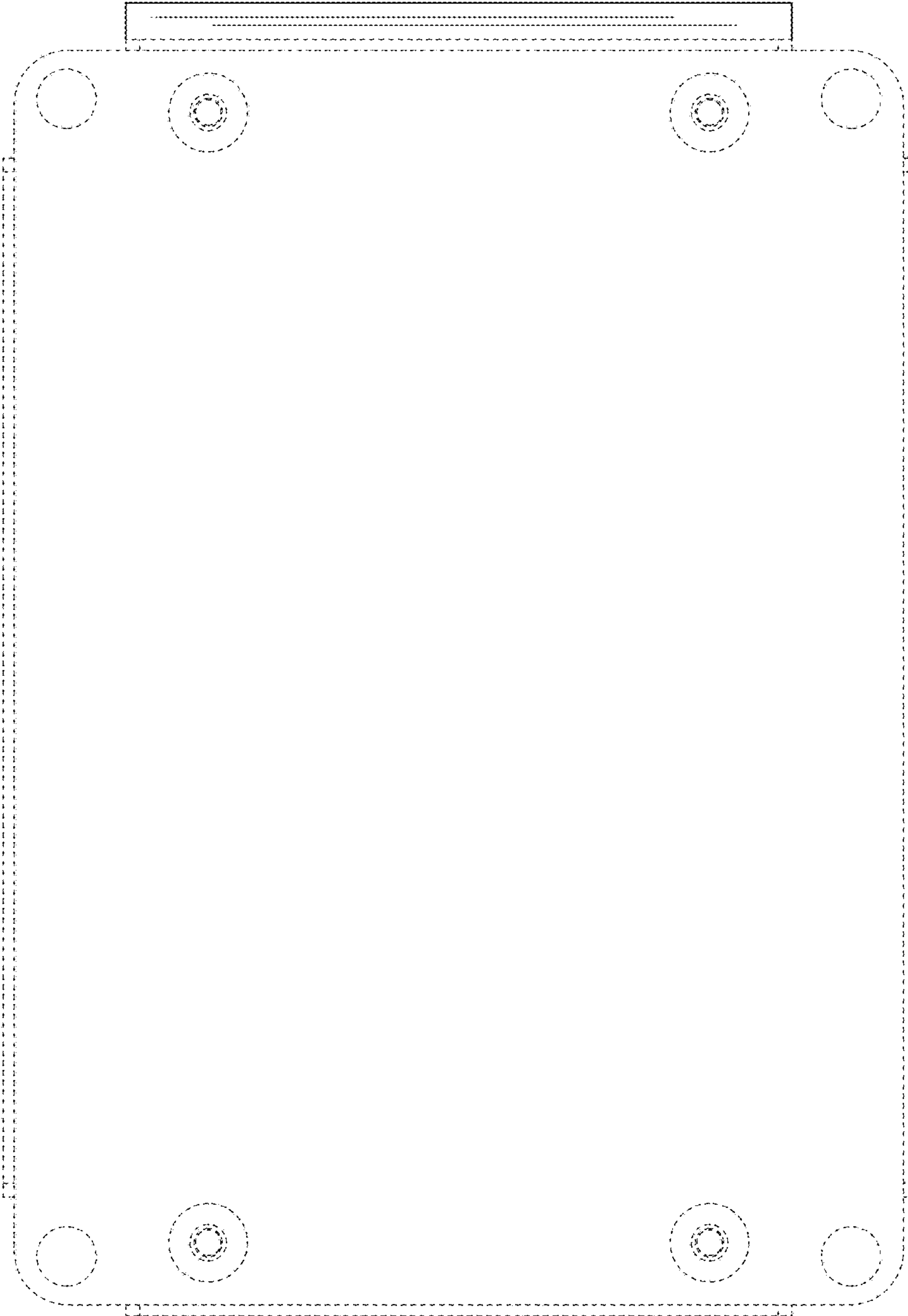


Fig. 6

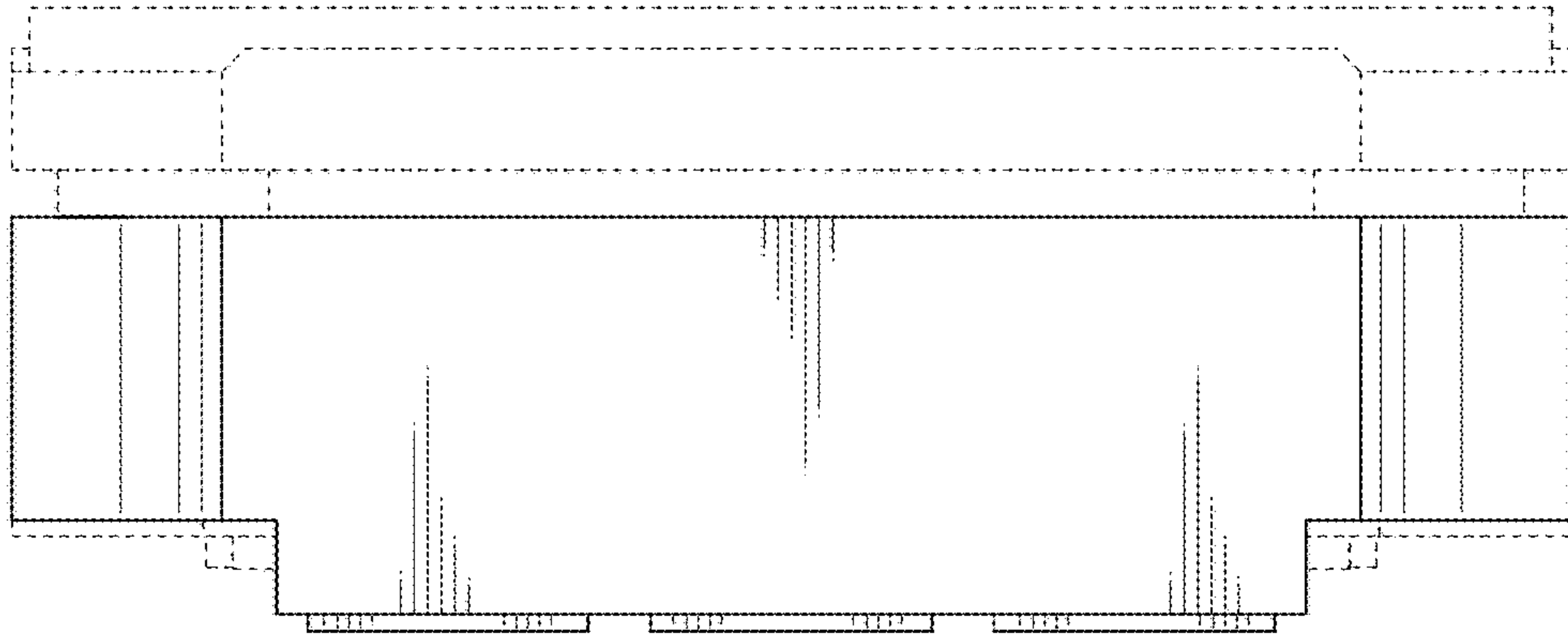


Fig. 5

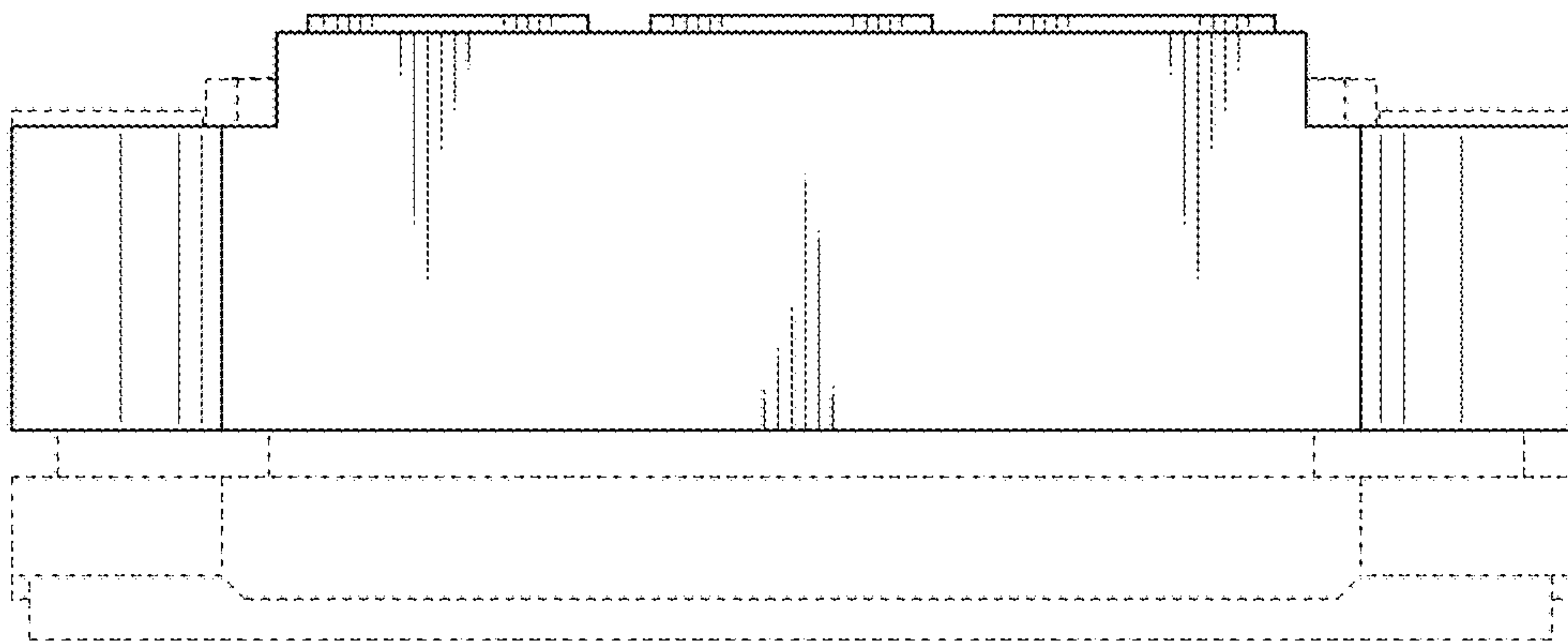


Fig. 7

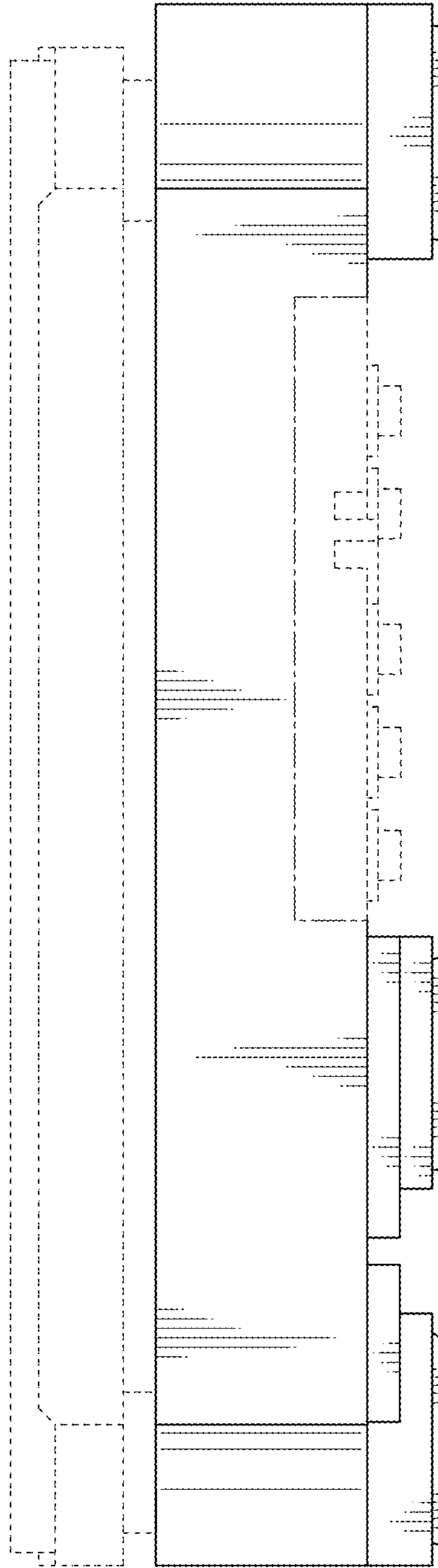




Fig. 8

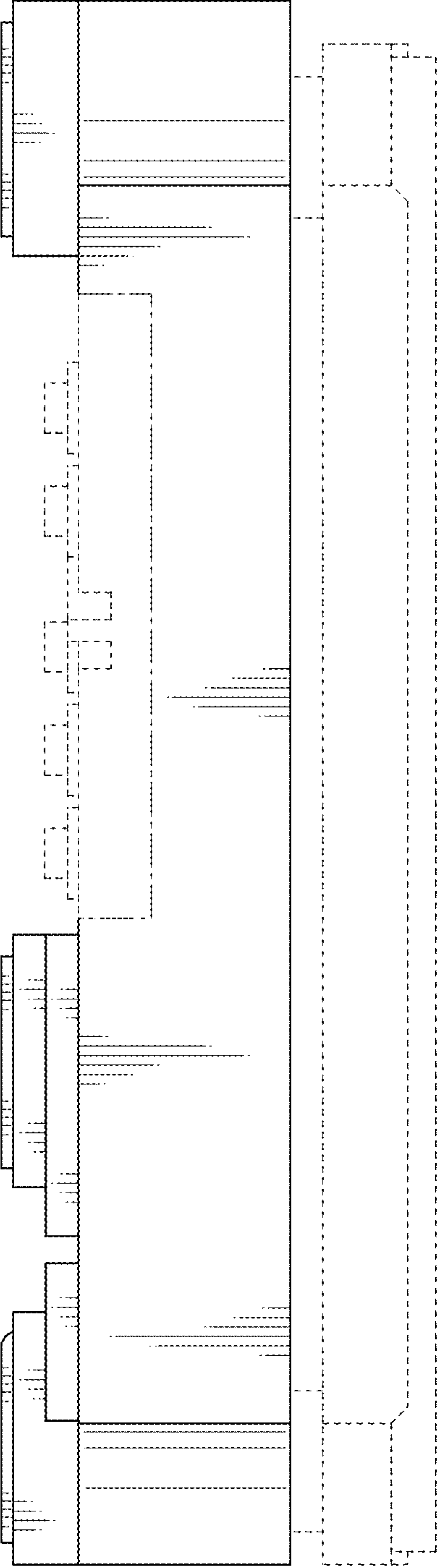


Fig. 9

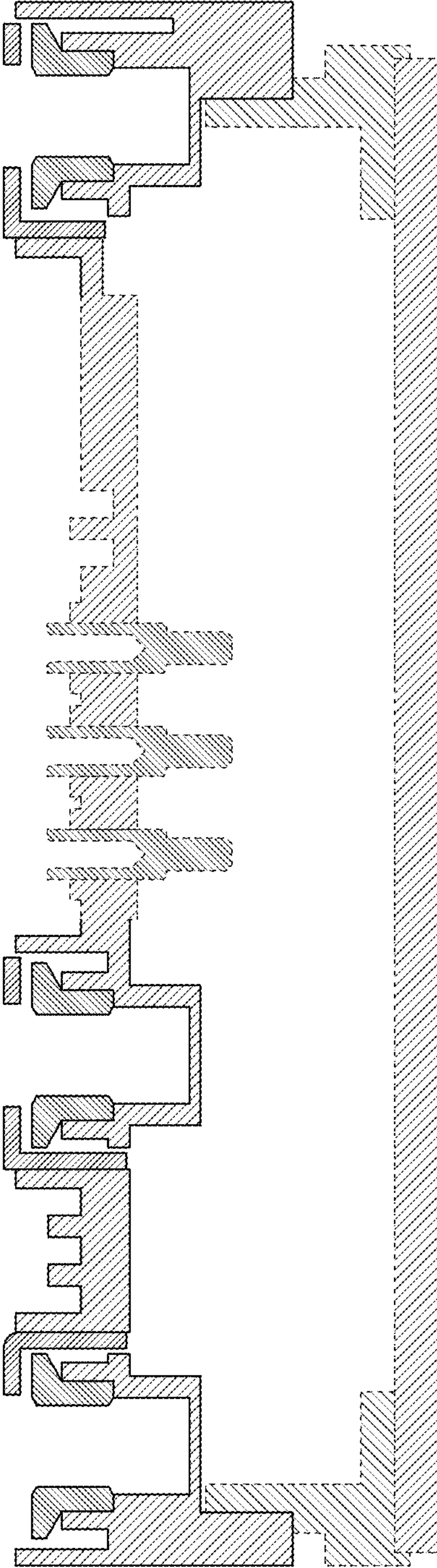


Fig. 10

